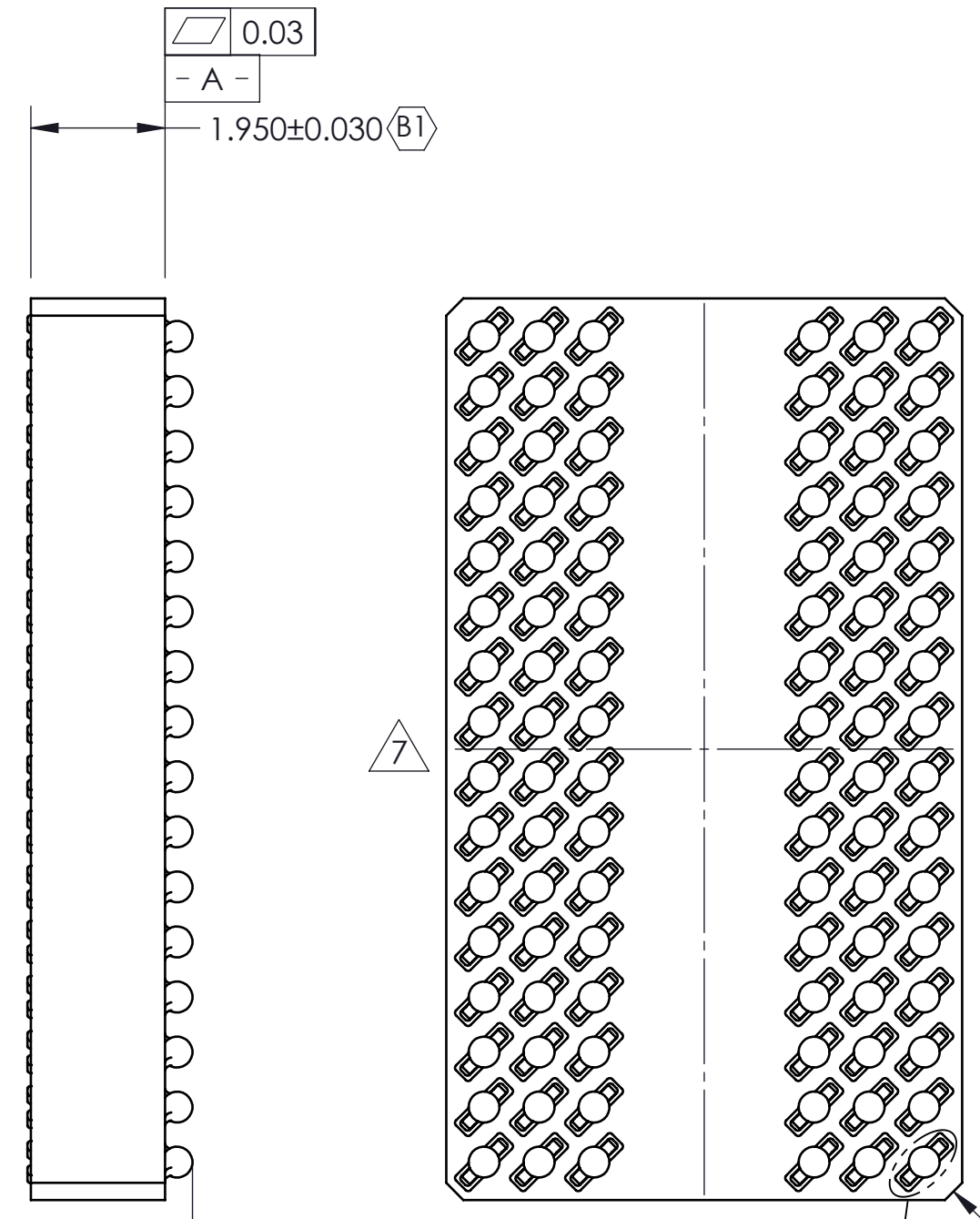
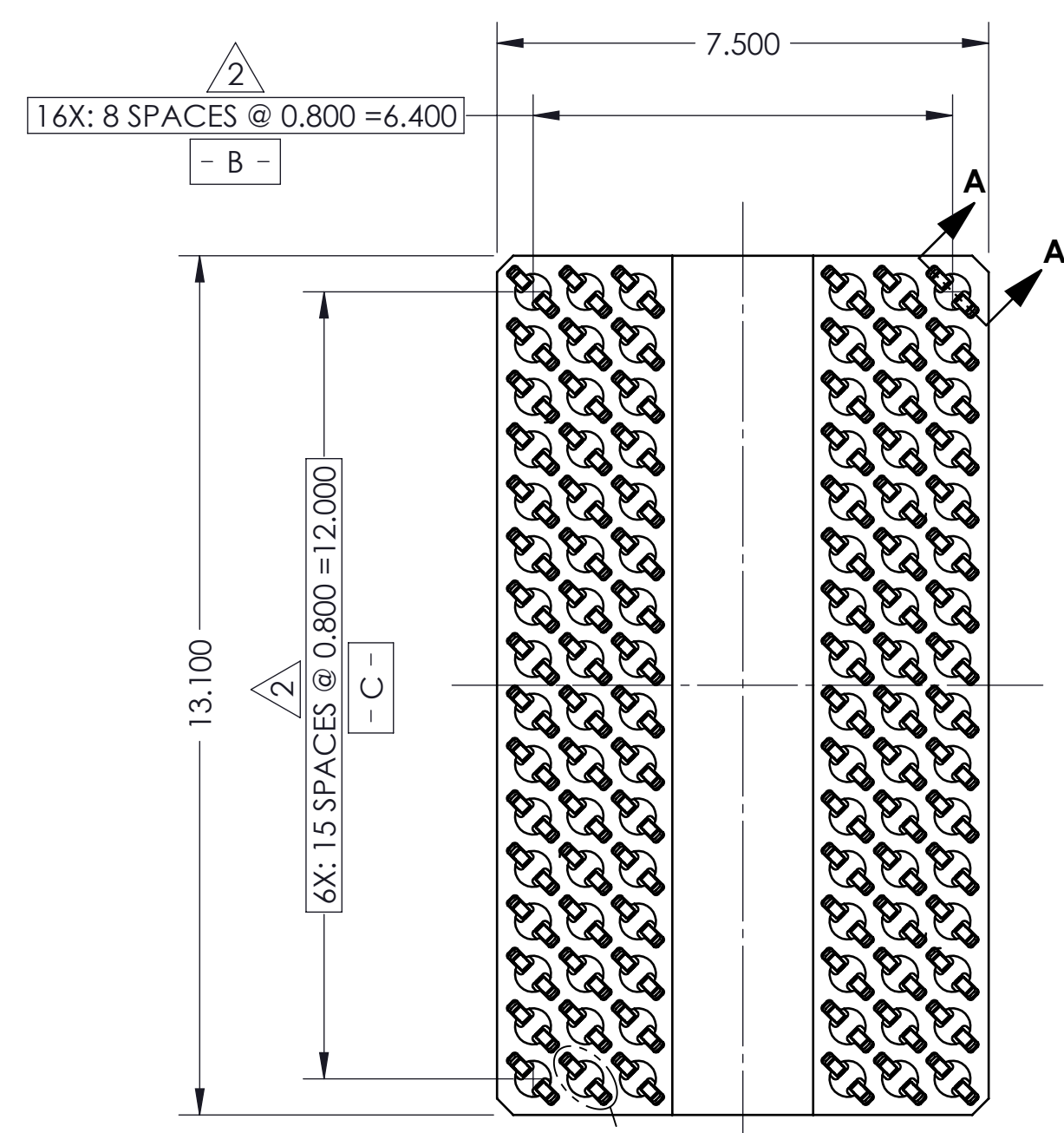
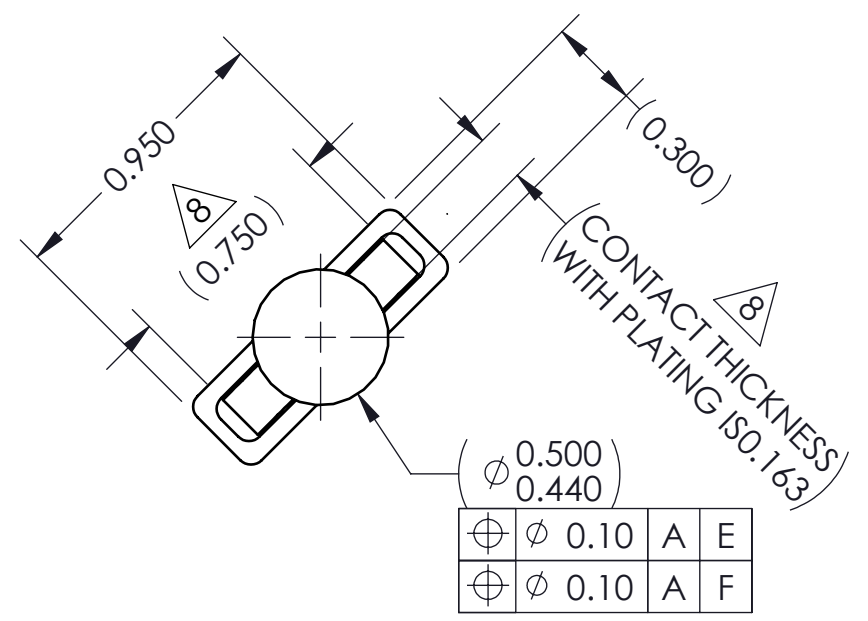
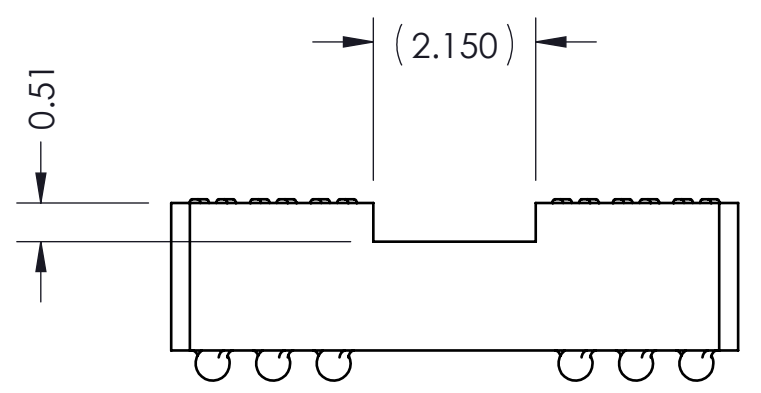


REV	ECO	BY	DESCRIPTION	APV	DATE
A	31470	AS	Initial Design	NSJ	01/30/14
B	31833	RS	1) Was 2.030 2) Was 78X 3) Was 108496-0015	NSJ	11/03/16

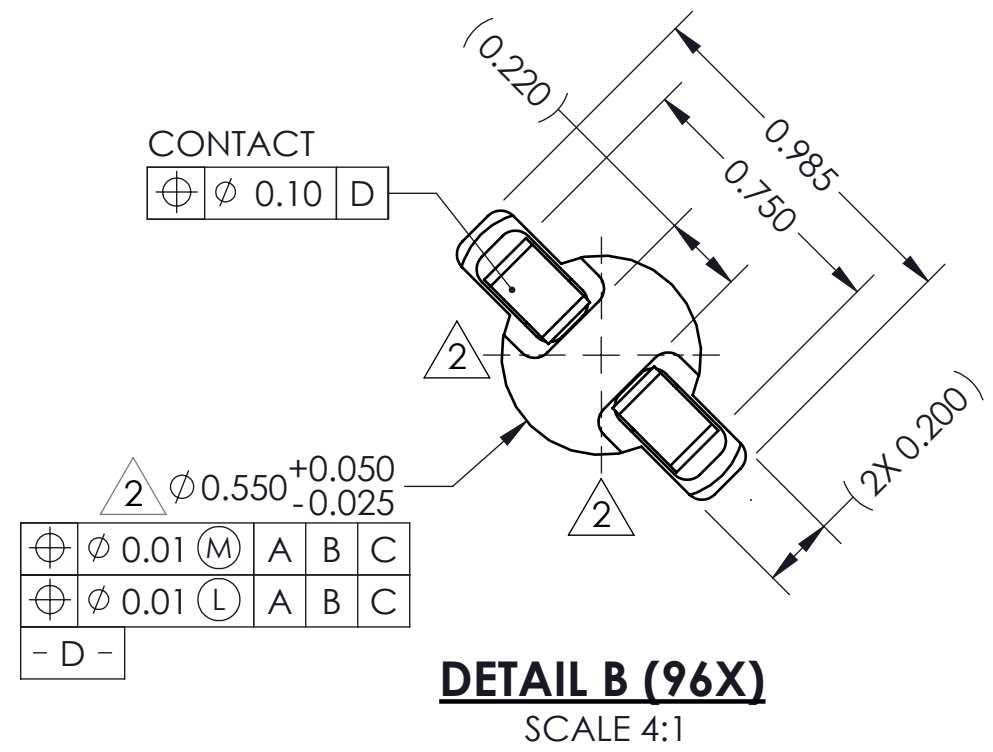
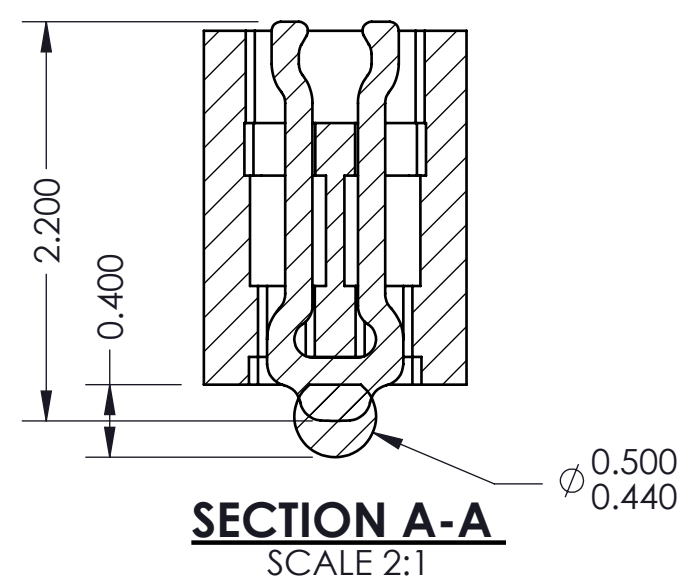


Notes:

- Reference HSI0 Technologies specification 103862-0004 for solder attachment.
 - Locates center of contact/slot.
 - Reference HSI0 Technologies specification 103863-0001 for application notes.
 - Footprint part number is 104311-0058.
 - Datum **- B -** and **- C -** are determined by $\phi 0.580$ opening in corner slots.
 - Unless otherwise noted, all features are located $\oplus 0.10$ A B C
- $\triangle 7$ **- E -** Center of ball pattern.
 $\triangle 8$ **- F -** Center of contact.



Parts List	
Part Number	Description
103864-0060	PRESS, DEVICE INSERT, GRYP 7.5X13.1 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4X53 (SOLD SEPARATELY)



HSIO technologies
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UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
ANGULAR: $\pm 1^\circ$
X.X ± 0.25
X.XX ± 0.10
X.XXX ± 0.050

INTERPRET GEOMETRIC TOLERANCING PER:

MATERIAL: SEE BOM
FINISH:

DO NOT SCALE DRAWING

NAME	DATE
AS	01/30/14
NSJ	01/30/14

LEGEND:

- \triangle NOTE CALLOUT
- \square REVISION CHANGE
- \circ ITEM NUMBER

HSIO TECHNOLOGIES, LLC.
13400 68th AVENUE NORTH
MAPLE GROVE, MINNESOTA 55311
763-447-6260

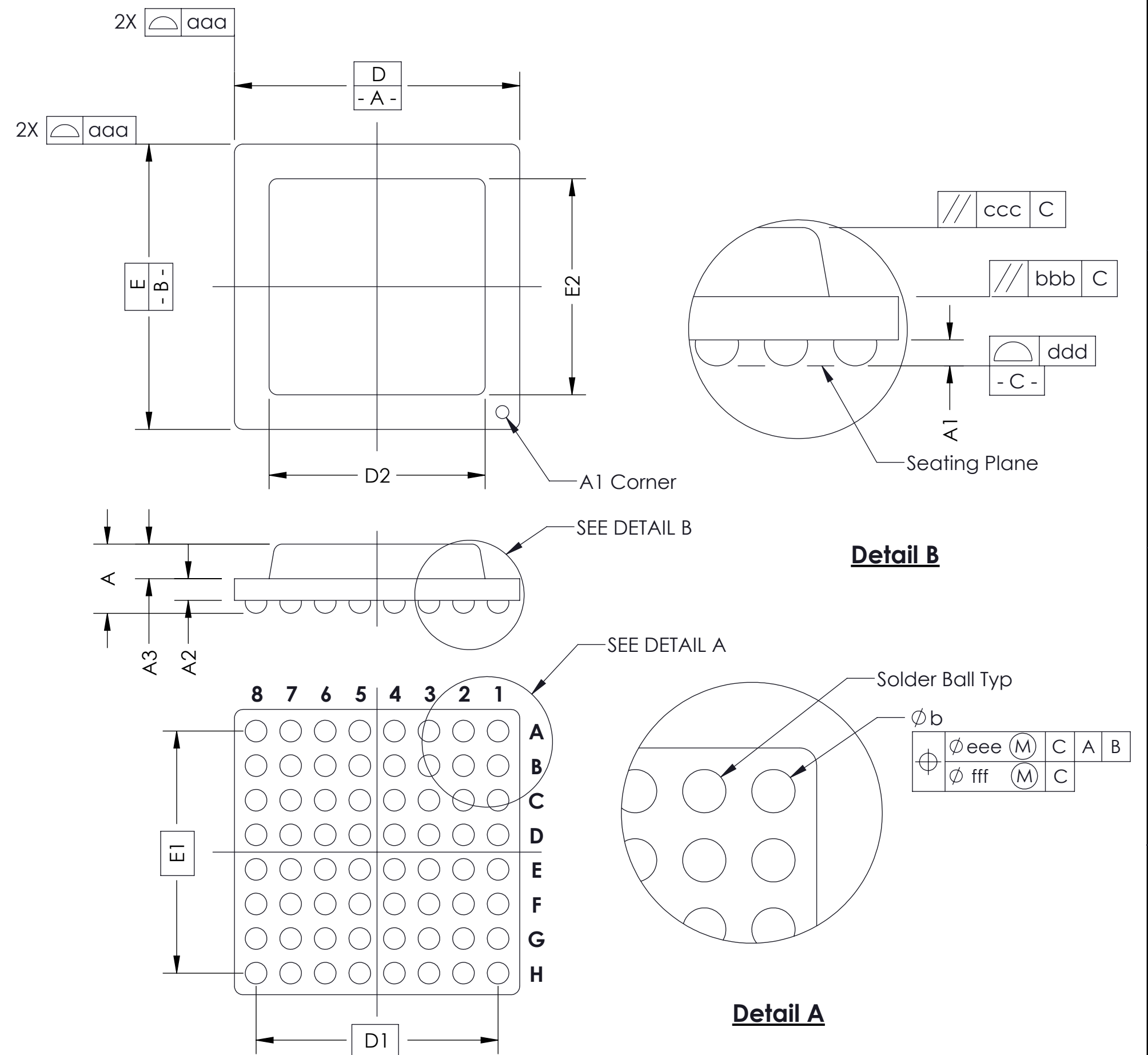
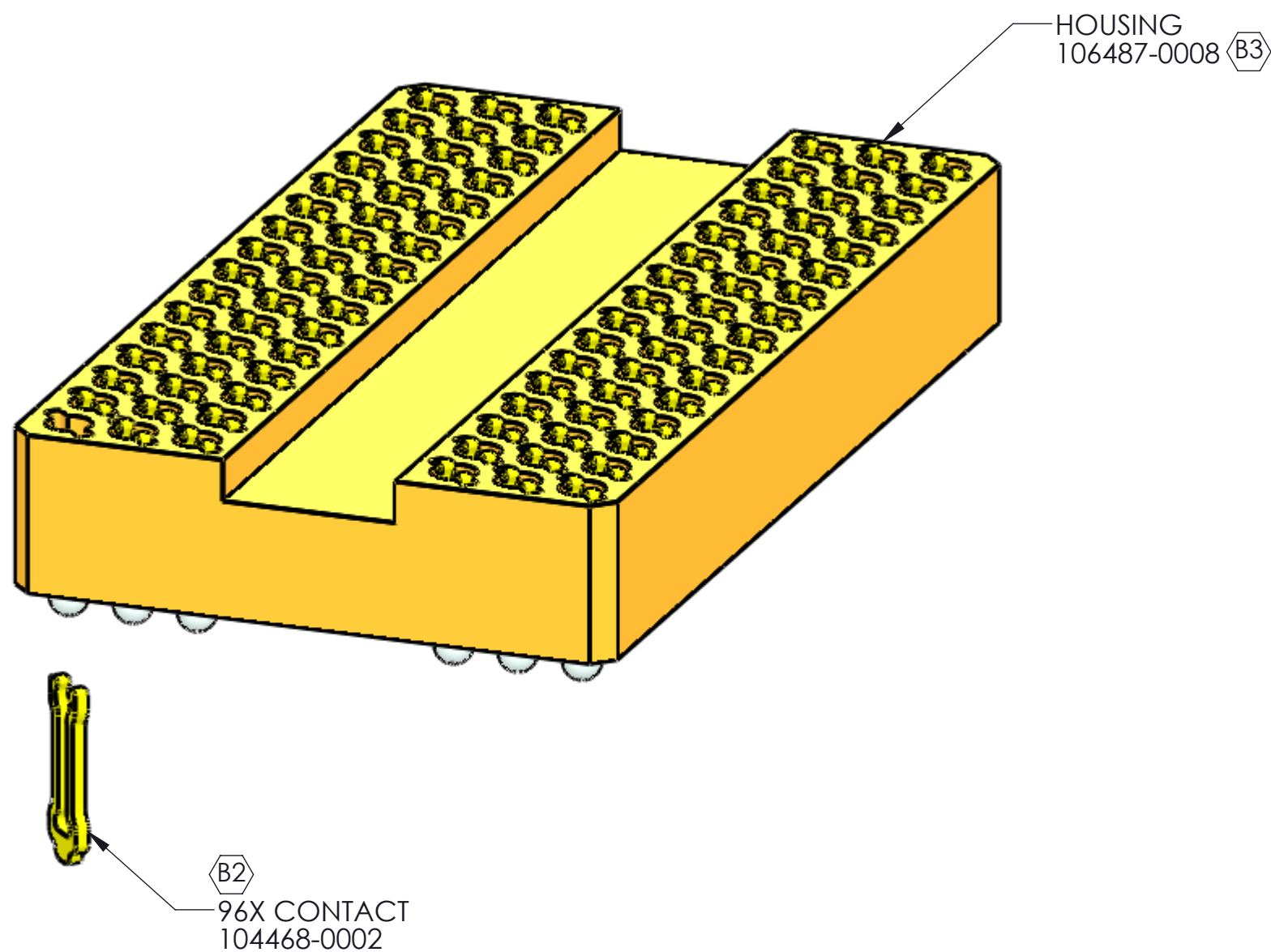
TITLE:
SCKT, 96GRY7.5X13.1-0.80,
W/EUTECTIC SOLDER BALLS

DWG. NO. **108493-0015** REV **B**

SCALE: 10:1 | SIZE: C | SHEET 1 OF 2

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	96	Package Size	D	7.50
Columns	ND	9	Ball Spacing	E	13.10
Rows	NE	16		D1	6.400
Pitch	e	0.80	Encapsulant/ Top Size	E1	12.000
Ball Size	b	0.45±0.05		D2	n/a
Total Thickness	A	N/A	Pattern Style	E2	n/a
Ball Height	A1	0.300 Min		Irregular*	
Substrate Thickness	A2	N/A	Perimeter Rows		n/a
Top Thickness	A3		Center Array		n/a
Form Tolerances					
Edge	aaa	0.20	Bottom	ddd	0.15
Substrate	bbb	0.20	Position	eee	0.20
top	ccc	0.20	Position	fff	0.08

All dimensions are in millimeters.
*See footprint specification for pattern details.



Generic Representation with Full Grid Array

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	HSI0 TECHNOLOGIES, LLC. 13400 68th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260
DIMENSIONS ARE IN MILLIMETERS	DRAWN	AS	
TOLERANCES:	CHECKED	NSJ	01/30/14
ANGULAR: ± 1°			TITLE: SCKT, 96GRY7.5X13.1-0.80, W/EUTECTIC SOLDER BALLS
X.X ±0.25			
X.XX ±0.10			DWG. NO. 108493-0015
X.XXX ±0.050			REV B
LEGEND:			SCALE: 10:1
△ NOTE CALLOUT			SIZE: C
◻ REVISION CHANGE			SHEET 2 OF 2
○ ITEM NUMBER			